

IN THE CLAIMS

Please amend the claims as shown below. This listing of claims replaces all prior versions and listings of claims in the Application.

1. (Currently Amended) A device for removing heat from an electronic component, comprising:
a heat sink adapted to couple to said electronic component and conduct heat therefrom; and
an appurtenance having fins, coupled to said heat sink and adapted to transfer said heat into a fluid medium, wherein said fins are oriented at an angle with respect to a plurality of flow streams of said fluid medium across said fins, wherein the space between most of said fins is substantially even, and wherein each flow stream of said plurality follows a unique direction.
2. (Previously Presented) The device as recited in Claim 1 wherein said fins comprise a substantially curved shape.
3. (Original) The device as recited in Claim 1 wherein said appurtenance comprises an integral part of said heat sink.
4. (Original) The device as recited in Claim 1 wherein each said flow stream of said plurality is oriented substantially orthogonal to each other said flow stream of said plurality.
5. (Previously Presented) The device as recited in Claim 4 wherein said fins are oriented in an aspect comprising a substantially obtuse angle from each said flow stream.

6-7. (Cancelled)

8. (Original) The device as recited in Claim 1 wherein said fins function to change each said unique direction.

9. (Currently Amended) A device for removing heat from an electronic component, comprising:

a heat sink adapted to couple to said electronic component and conduct heat therefrom; and

an appurtenance having fins, coupled to said heat sink and adapted to transfer said heat into a fluid medium, wherein said fins are curved and function to gradually change the direction of flow of each flow stream of a plurality of flow streams directed towards said appurtenance, wherein the space between most of said fins is substantially even, and wherein each flow stream of said plurality follows a unique direction.

10. (Original) The device as recited in Claim 9 wherein said appurtenance comprises an integral part of said heat sink.

11. (Original) The device as recited in Claim 9 wherein each said flow stream of said plurality is oriented substantially orthogonal to each other said flow stream of said plurality.

12. (Withdrawn)

13. (Original) The device as recited in Claim 9 wherein said fins function to effect a change in each said unique direction and wherein said change comprises a gradual change.

14. (Currently Amended) A method for removing heat from an electronic component, comprising:

directing a plurality of flow streams of a fluid medium towards an appurtenance having a plurality of fins, said appurtenance coupled to a heat sink conducting heat from said electronic component, wherein each flow stream of said plurality of flow streams is disposed to approach said appurtenance from a direction different from each other flow stream of said plurality of flow streams; and

changing said direction within a contour described by a space between each said fin of said plurality of fins by interaction with said fins, wherein said space between most of said fins is substantially even.

15. (Cancelled)

16. (Previously Presented) The method as recited in Claim 14, wherein said fins are oriented in an aspect comprising a substantially obtuse angle from each said flow stream.

17. (Withdrawn)

18. (Original) The method as recited in Claim 14 wherein said fins comprise a substantially curved shape and wherein said changing is performed gradually.

19. (Original) The method as recited in Claim 18 wherein each said flow stream of said plurality is oriented substantially orthogonal to each other said flow stream of said plurality.

20. (Withdrawn)